

QTLP630C-2 HER
QTLP630C-4 Green
QTLP630C-B Blue

QTLP630C-3 Yellow
QTLP630C-7 AlGaAs Red

Surface Mount LED Lamp, Standard Bright 0805

Features

- Small footprint – 2.0(L) X 1.25(W) X 1.1(H) mm
- Wide viewing angle of 140°
- Water clear optics
- Moisture-proof packaging
- Available in 0.315" (8mm) width tape on 7" (178mm) diameter reel; 2,000 units per reel

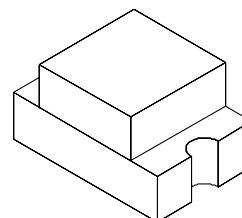
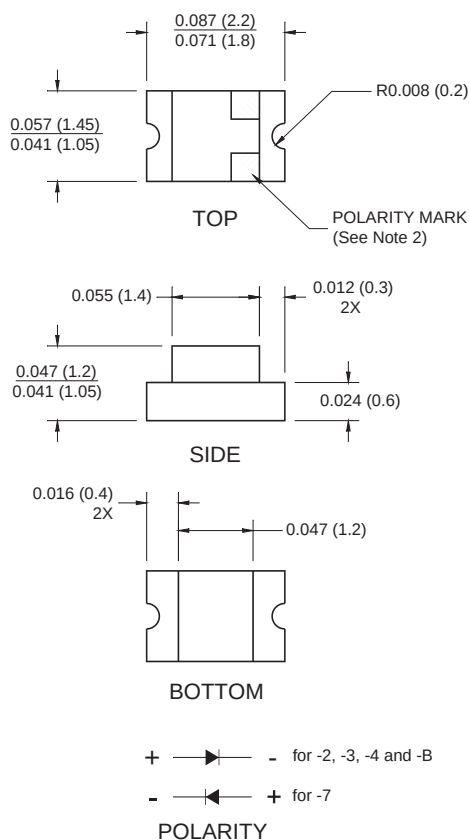
Applications

- Keypad backlighting
- Push-button backlighting
- LCD backlighting

Description

These surface mount chip LEDs are designed to fit industry standard footprint. Low profile and wide viewing angle make these LEDs ideal choices for backlighting applications and panel illumination.

Package Dimensions



NOTE:

1. Dimensions for all drawings are in inches (mm).
2. Cathode for -2, -3, -4 and B. Anode for -7.

Absolute Maximum Ratings ($T_A = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	QTLP630C					Unit
		-2	-3	-4	-7	-B	
Continuous Forward Current	I_F	30	30	30	30	30	mA
Peak Forward Current ($f = 1.0\text{ KHz}$, Duty Factor = 1/10)	I_{FM}	160	160	160	180	100	mA
Reverse Voltage ($I_R = 10\text{ }\mu\text{A}$)	V_R	5	5	5	5	5	V
Power Dissipation	P_D	84	84	84	72	135	mW
Operating Temperature	T_{OPR}	-40 to +85					$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-40 to +90					$^{\circ}\text{C}$
Lead Soldering Time	T_{SOL}	260 for 5 sec					$^{\circ}\text{C}$

Electrical/Optical Characteristics ($T_A = 25^{\circ}\text{C}$)

Parameter	Symbol	QTLP630C					Condition
		-2	-3	-4	-7	-B	
Luminous Intensity (mcd)							
Minimum	I _V	5	5	6	10	15	I _F = 20mA
Typical		10	10	10	20	20	
Forward Voltage (V)							
Maximum	V _F	2.8	2.8	2.8	2.4	4.5	I _F = 20mA
Typical		2.0	2.0	2.1	1.9	3.8	
Wavelength (nm)							
Peak	λ _P	635	585	565	660	430	I _F = 20mA
Dominant	λ _D	630	590	570	645	465	
Spectral Line Half Width (nm)	Δ _λ	45	35	30	20	65	I _F = 20mA
Viewing Angle (°)	2Θ ¹ / ₂	140	140	140	140	140	I _F = 20mA

Typical Performance Curves

Fig. 1 Forward Current vs. Forward Voltage

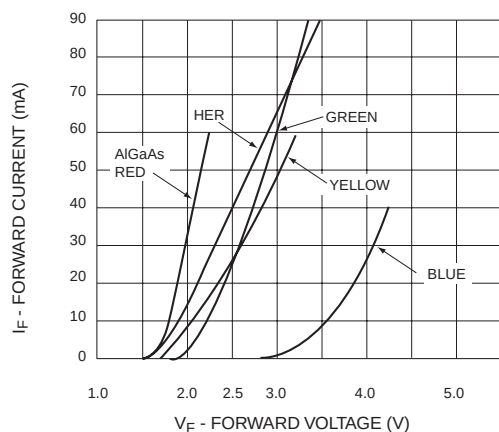


Fig. 2 Relative Luminous Intensity vs. DC Forward Current

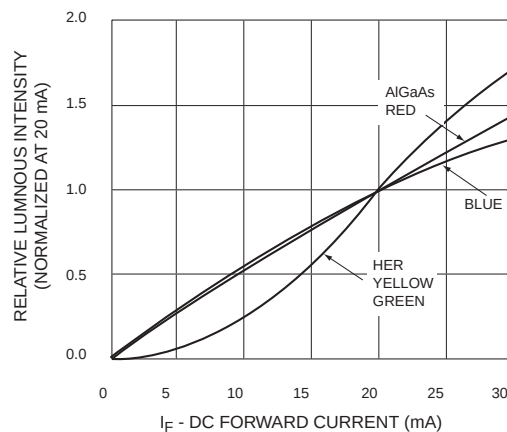


Fig. 3 Relative Intensity vs. Peak Wavelength

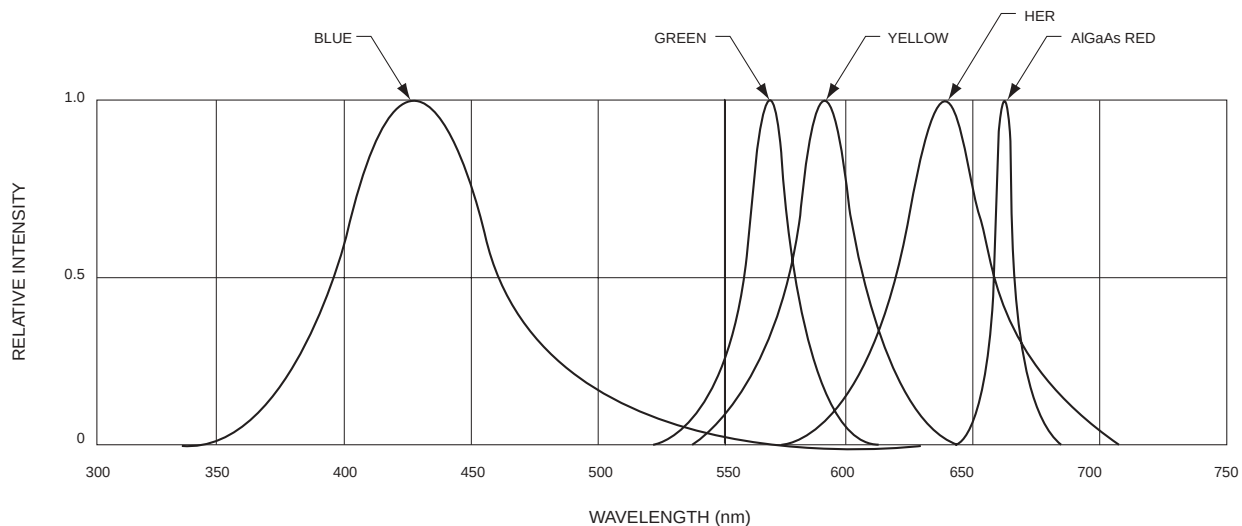


Fig.4 Radiation Diagram

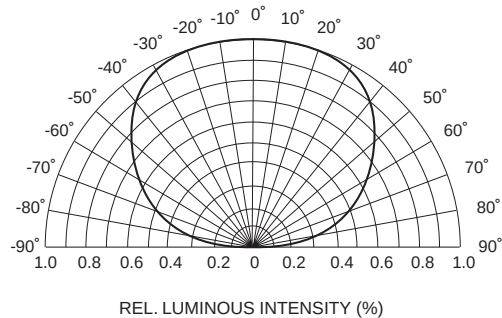
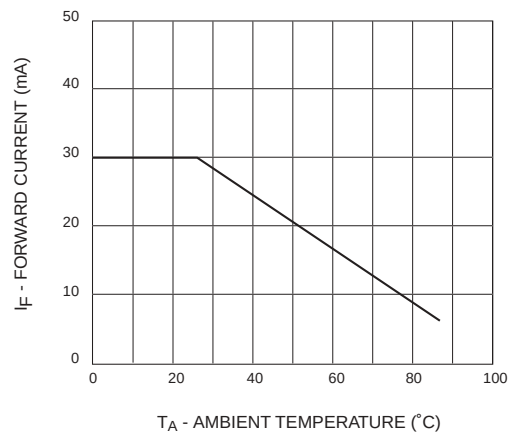
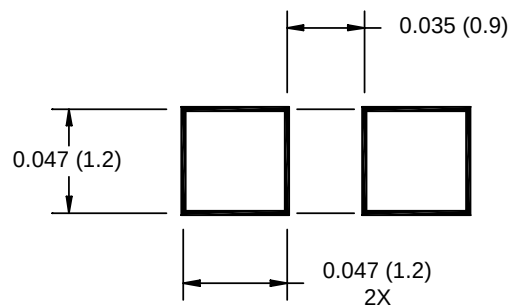


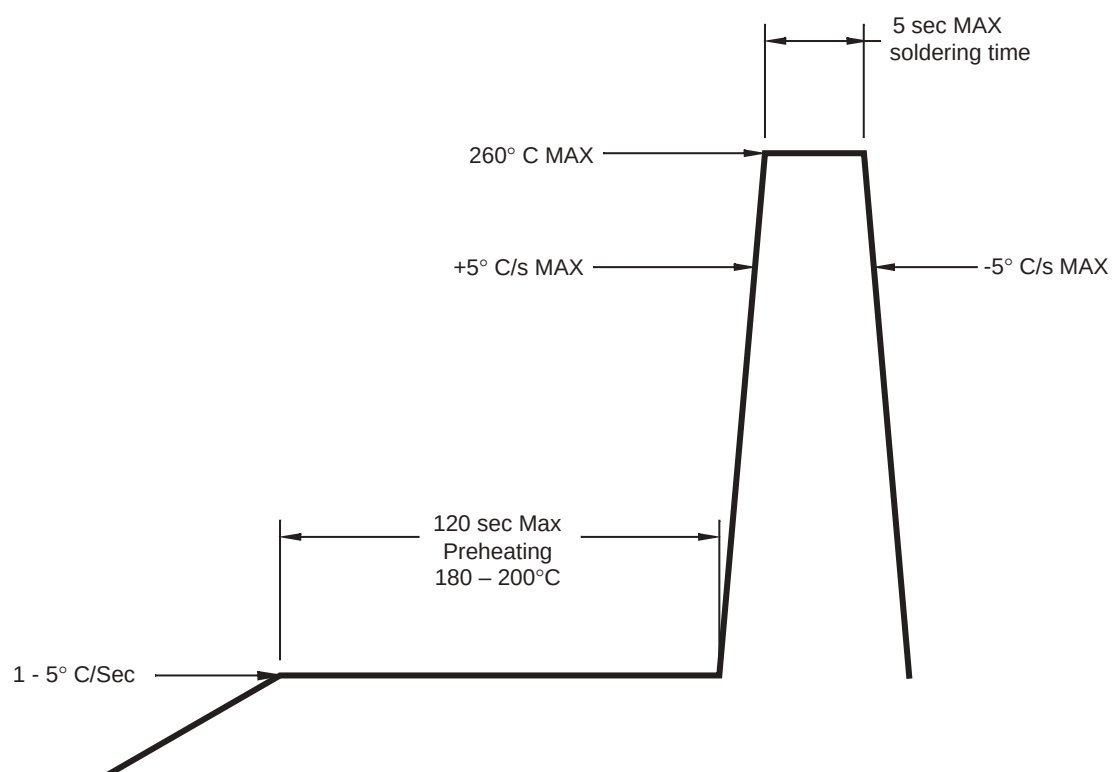
Fig.5 Maximum Forward Current vs. Ambient Temperature



Recommended Printed Circuit Board Pattern



Recommended IR Reflow Soldering Profile



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